## 3M<sup>™</sup> Mini-Clamp Socket

2 mm, Surfacemount, Right Angle





- Low profile design minimizes overall thickness
- Compact design saves board space
- Multiple PCB locating post layouts to ensure competitive compatibility
- Solder tab design helps ensures a reliable solder joint
- Mating Latch feature provides a reliable interconnection in demanding applications
- High number of mating cycles (300)
- Maximum current rating of 3 Amps
- Dust cover accessory available for use in harsh environment
- Available in Tape and Reel
- RoHS Compliant. See the Regulatory Information Appendix (RIA) in the "RoHS compliance" section of www.3Mconnector.com for compliance information (RIA E1 & C1 apply)

Date Modified: July 14, 2011

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## **Physical**

**Insulation:** 

Material: LCP Flammability: UL 94V-0 Color: Black

**Contact:** 

Material: Copper Alloy

**Plating:** 

Underplating: 100 µ" [2.54 µm) Ni

Wiping Area: 0.2 μm [8 μ"] min Gold with Lubricant

Solder Tails: Gold Flash

Solder Tabs: 120 μ" min [3 μm min) Matte Sn over 40 μ"-120 μ" [1-3 μm] Ni

Marking: 3M Logo, Position Indicator, Insulator Material

Mating Compatibility: 371 Series

## **Electrical**

**Current Rating:** 3.0 A **Voltage Rating:** 32 V

**Insulation Resistance:**  $1,000 \,\mathrm{M}\Omega$  minimum at  $500 \,\mathrm{V}_{\mathrm{DC}}$ 

Withstanding Voltage: 1,000 V<sub>RMS</sub> for 1 minute

## **Environmental**

**Temperature Rating:** -20°C to +85°C ambient (1.0 A max.)

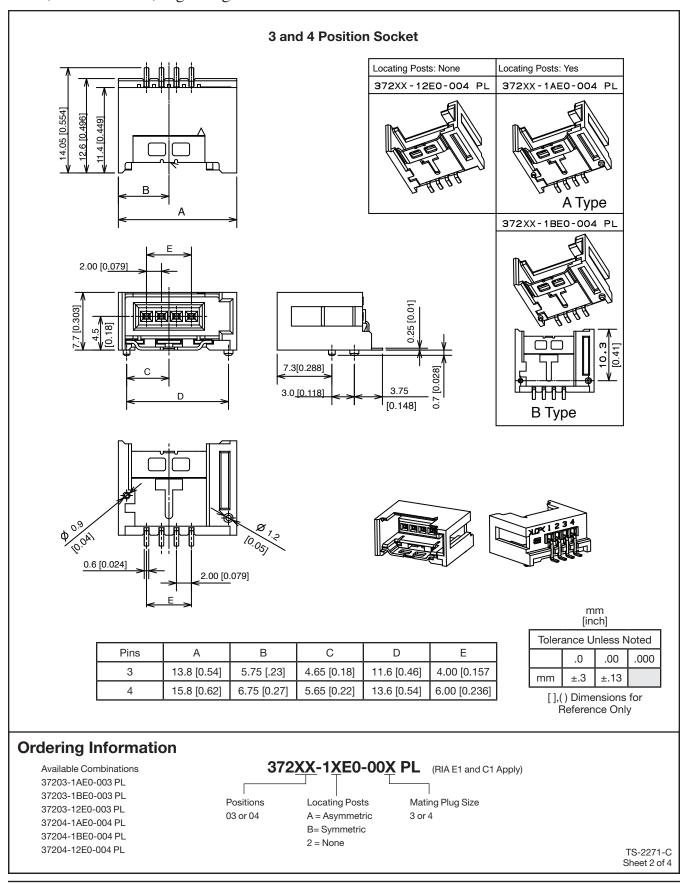
-20°C to +75°C ambient (2.0 A max.) -20°C to +60°C ambient (3.0 A max.) (Note: UL rating is 65 C at 3.0 A, 32 V)

**Process Rating:** 260°C max. SMT reflow (J-STD-020 MSL1)

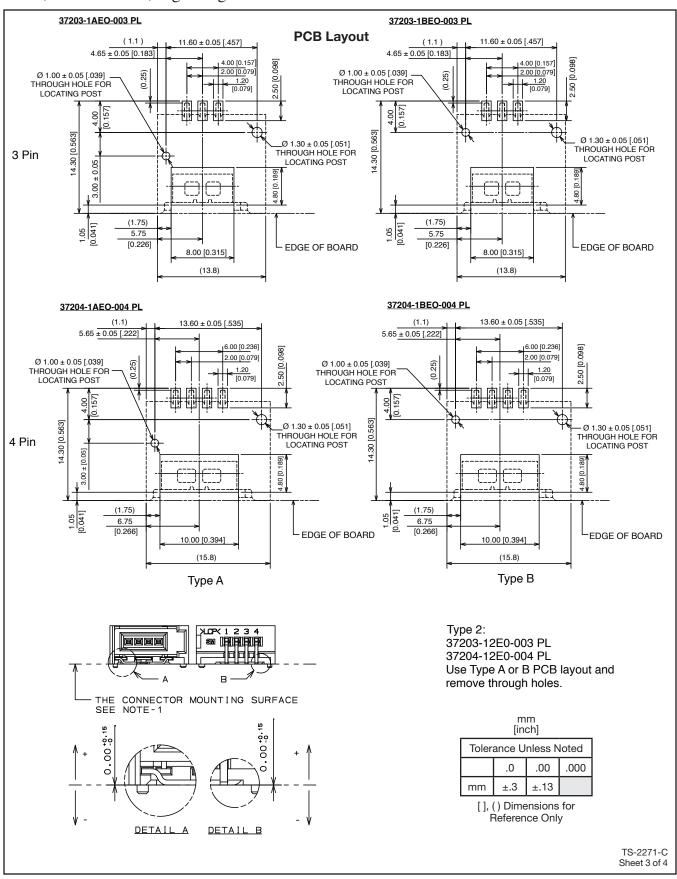
390°C max. for soldering iron

UL File No.: E68080

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